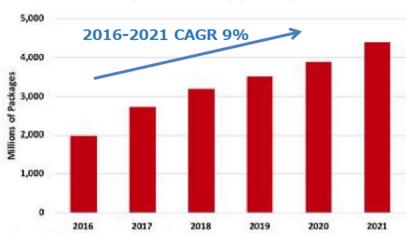
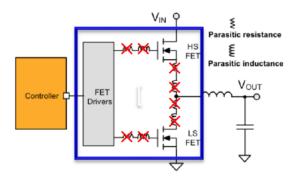
Power QFN with Copper clip market



Source: TechSearch International Inc.

Target applications; High current DCDC converter Step down DC-DC converter



Required characteristics:

Low Parasitic Inductance and Resistance

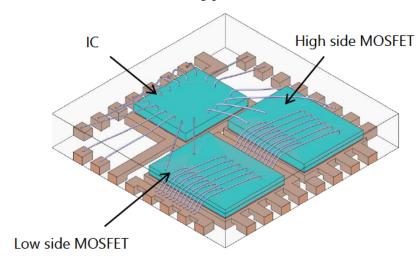
Clip process flow image

Case study: For multi chips 1. Solder screen printing 2. Die attach 3. Solder dispense &Flux cleaning 4. Clip attach & Reflow Transfer Mold Post Mold Cure Laser Mark Package Sawing Test

Specific study case

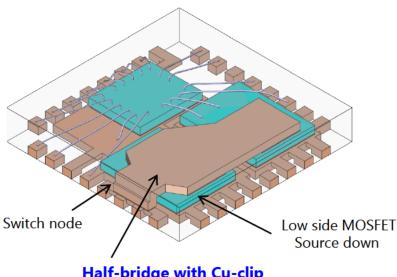
- Synchronous rectification type step-down DCDC
- · PKG: Power QFN
- Chip: IC+MOSFET×2(Half-bridge) 3in1

Current) Wire Type



- ·High side MOS; Drain down
- ·Low side MOS; Drain down
- ·Wire; Pd-Cu Φ30μm
- MOSFET source 12wires **X**Staggered wiring

Suggestion) Cu-Clip Type



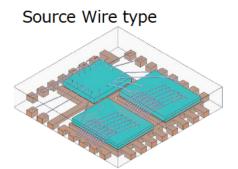
Half-bridge with Cu-clip

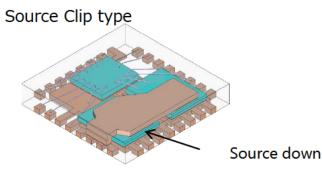
- MOSFET Wire → Cu-clip(Half bridge)
- MOSFET Low side →Source down
- Switch node is small

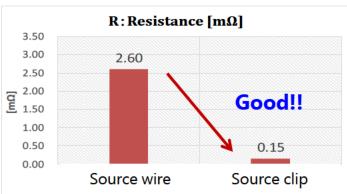
⇒Low Inductance and Resistance

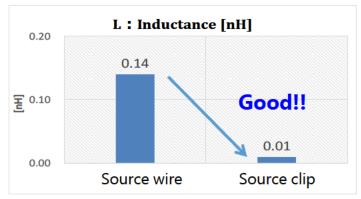
Target application Current: 10~30A

Advantage: Low Electrical Parasitic properties







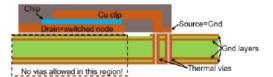


Source down advantage

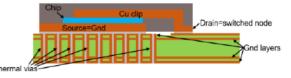
Mount the source electrode that becomes the GND potential directly on a large-area substrate.

Low characteristic loss: heat dissipation and resistance

Normal)Drain down

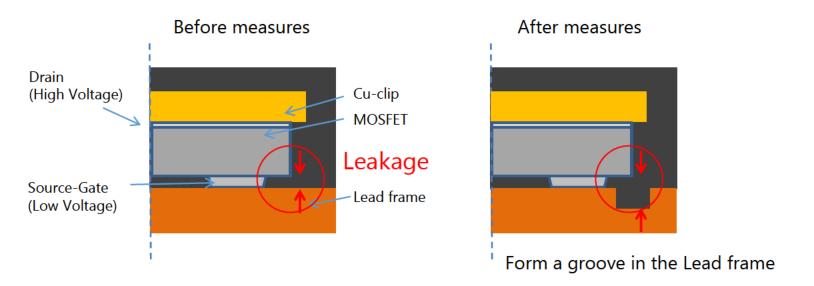


New)Source down



Source: Infineon

Source down structure for High Voltage (VDS=100V≦)



Problem:

• Leakage becomes a problem only with the height of the joint bump.

Take measures

• Element side(High Voltage) and connection lead(Low Voltage)Secure a certain distance or more.

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